US00D733311S

(12) **United States Design Patent**
Takanishi et al.

(10) **Patent No.: US D733,311 S**
(45) **Date of Patent: ** Jun. 30, 2015**

(54) **THERMAL PAD**

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(**) Term: **14 Years**

(21) Appl. No.: **29/485,330**

(22) Filed: **Mar. 18, 2014**

(30) **Foreign Application Priority Data**

Sep. 19, 2013 (JP) D2013-021728

(51) **LOC (10) Cl.** **24-04**
(52) **U.S. Cl.**
USPC **D24/206**
(58) **Field of Classification Search**
USPC D2/639, 728, 853, 999; D24/188–190, D24/206; 126/108–111, 114, 263.02; 219/464.1
CPC A44C 11/002; A44C 27/00; D04D 1/04
See application file for complete search history.

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Assistant Examiner — Darcey E Heflin
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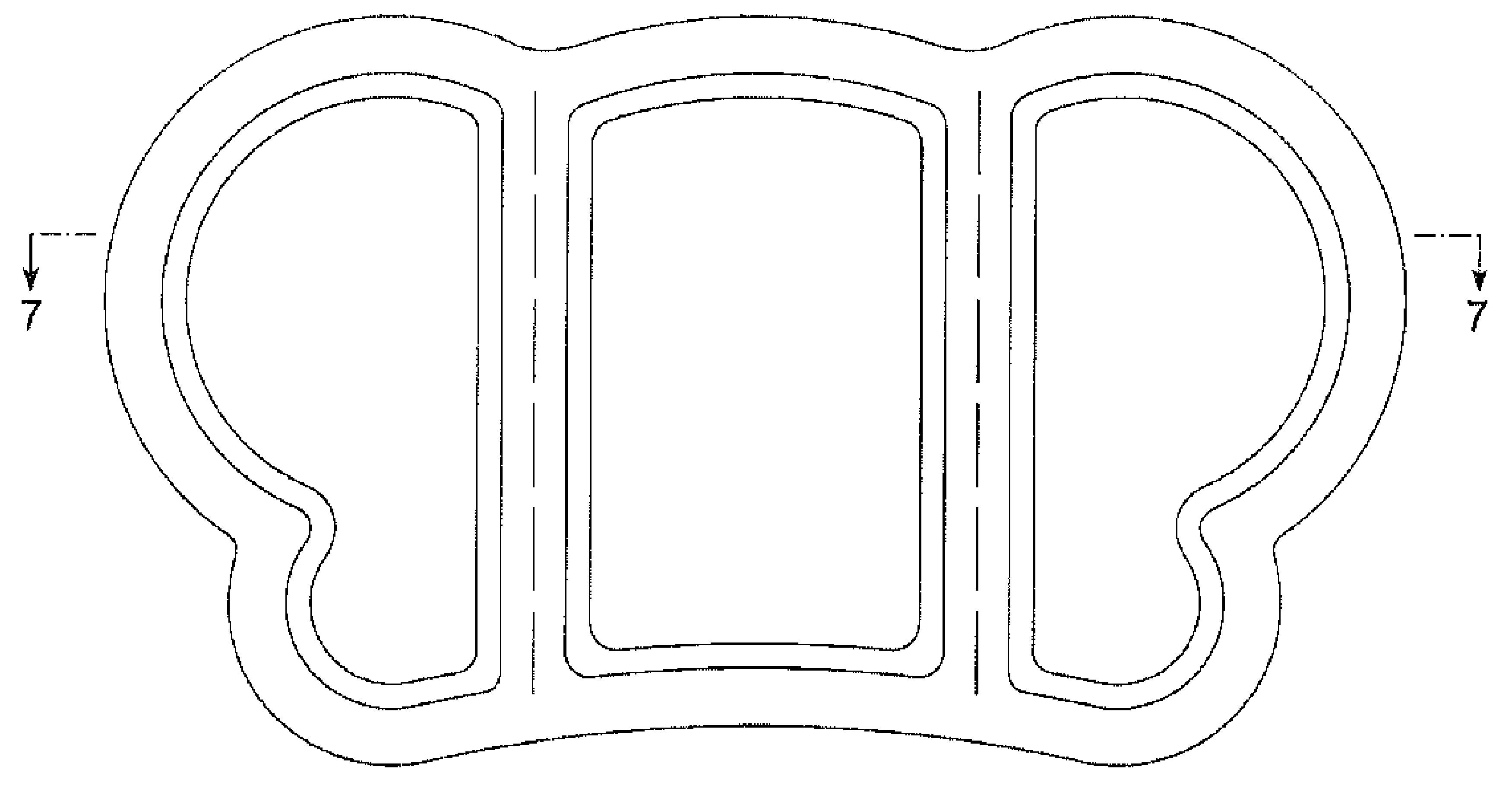
(57) **CLAIM**

The ornamental design for a thermal pad, as shown and described.

DESCRIPTION

FIG. **1** is a front view of a thermal pad of the present invention.
FIG. **2** is a rear view of the thermal pad of FIG. **1**.
FIG. **3** is a top plan view of the thermal pad of FIG. **1**.
FIG. **4** is a bottom view of the thermal pad of FIG. **1**.
FIG. **5** is a right side view of the thermal pad of FIG. **1**.
FIG. **6** is a left side view of the thermal pad of FIG. **1**.
FIG. **7** is an end view taken along the line **7-7** of the thermal pad of FIG. **1**.
FIG. **8** is an enlarged view taken along the line **8-8** of the thermal pad of FIG. **7**.
FIG. **9** is an enlarged view taken along the line **9-9** of the thermal pad of FIG. **7**; and,
FIG. **10** is a rear view of the thermal pad of FIG. **1** from which the release sheet has been removed for clarity of disclosure, it being understood that the stippled areas indicate adhesive surfaces.
The broken lines in the drawings represent claimed perforations on the thermal pad.

1 Claim, 9 Drawing Sheets



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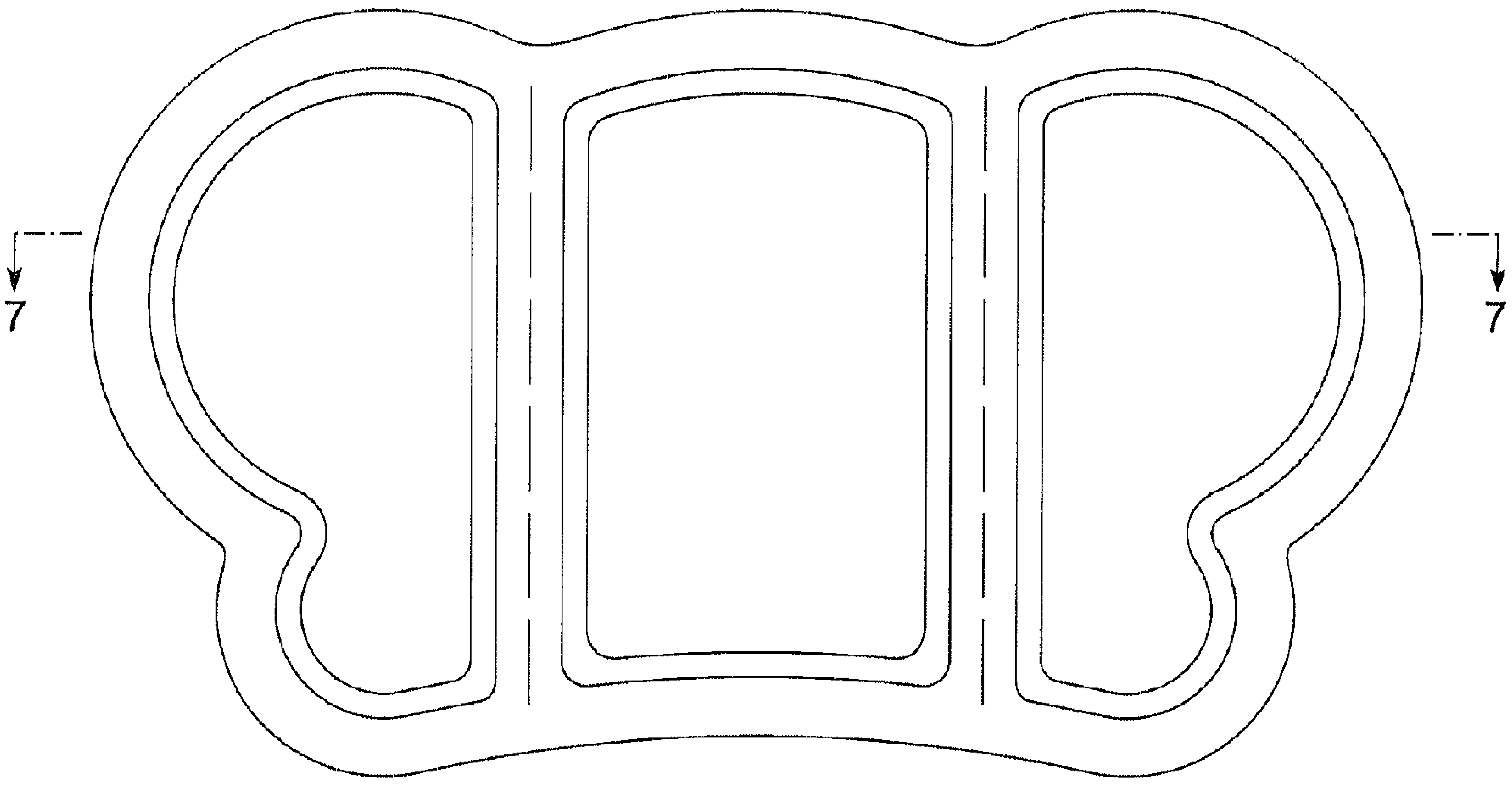

FIG. 1

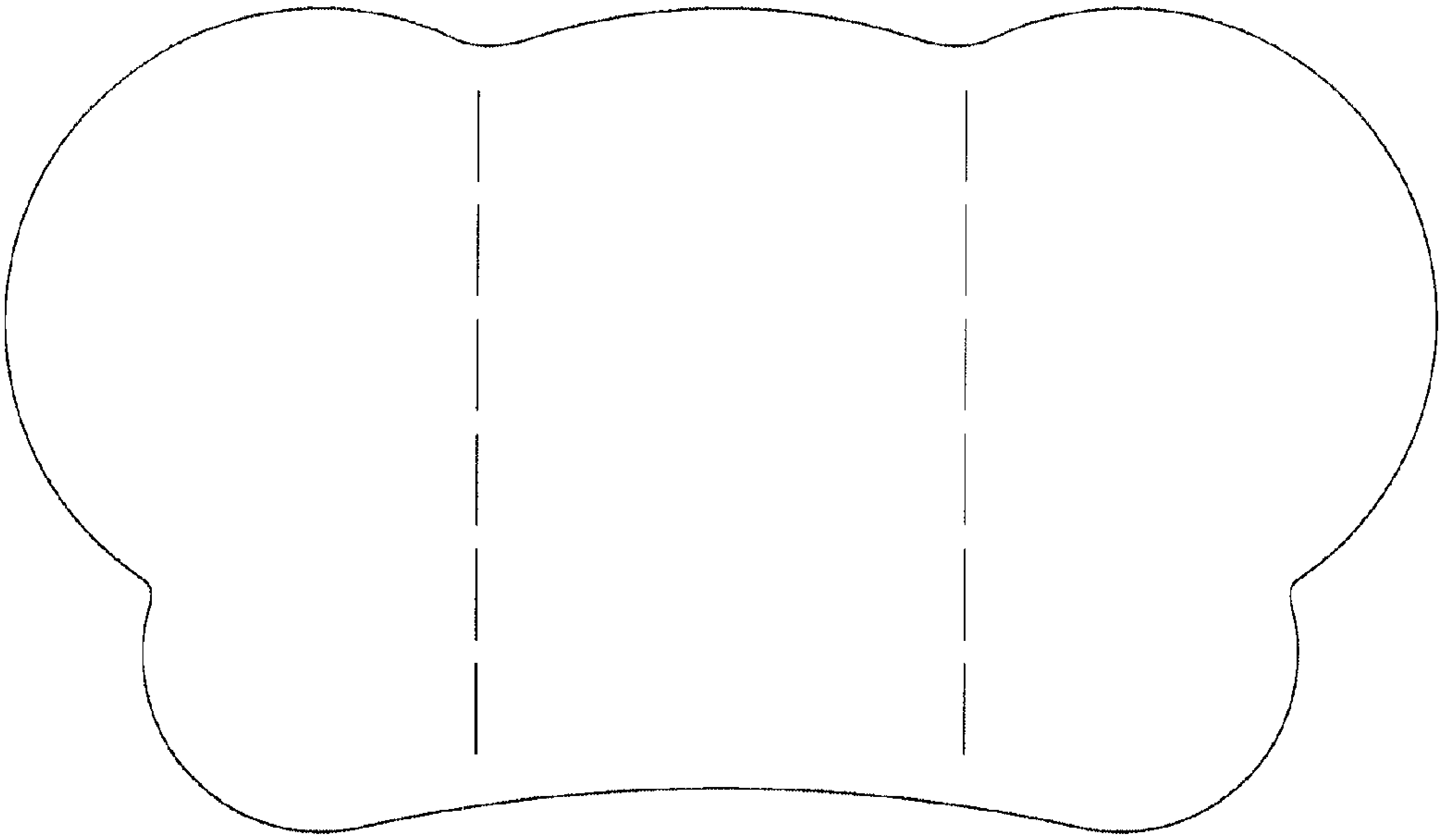

FIG. 2

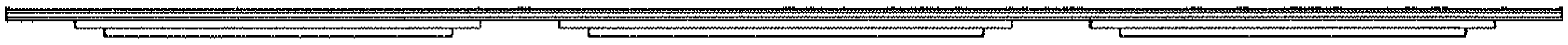

FIG. 3

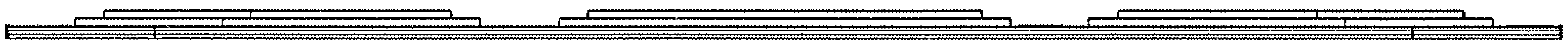

FIG. 4

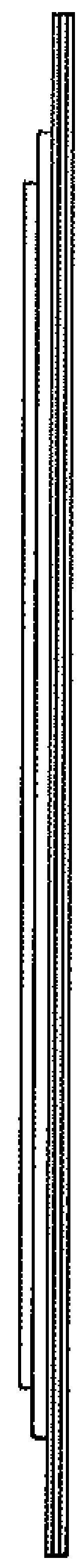

FIG. 5

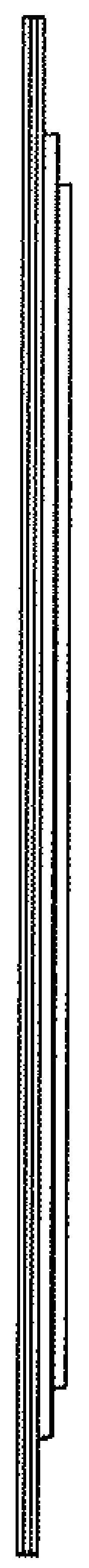

FIG. 6

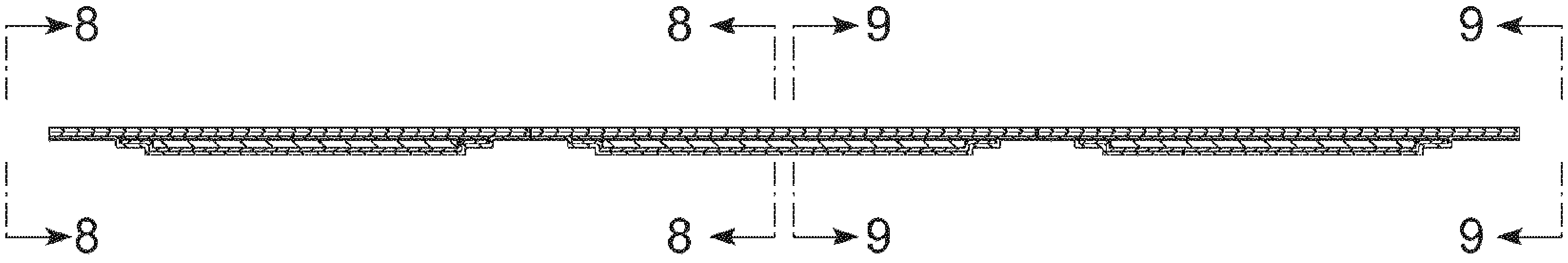

FIG. 7

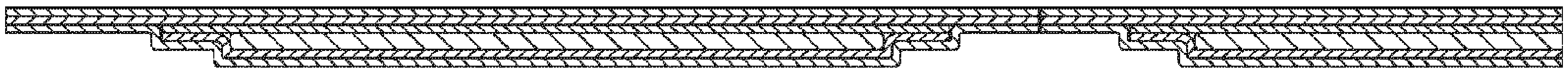

FIG. 8

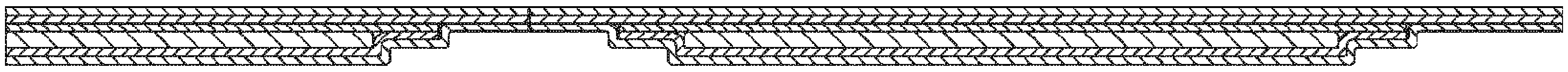

FIG. 9

UNITED STATES PATENT AND TRADEMARK OFFICE

CERTIFICATE OF CORRECTION

PATENT NO. : D733,311 S
APPLICATION NO. : 29/485330
DATED : June 30, 2015
INVENTOR(S) : Takanishi et al.

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Delete Drawing Sheets 7-9 and substitute therefore with the attached Drawing Sheets 7-9 consisting of replacement FIGS. 7-9.

Signed and Sealed this
Twenty-ninth Day of December, 2015

Michelle K. Lee

Michelle K. Lee
Director of the United States Patent and Trademark Office

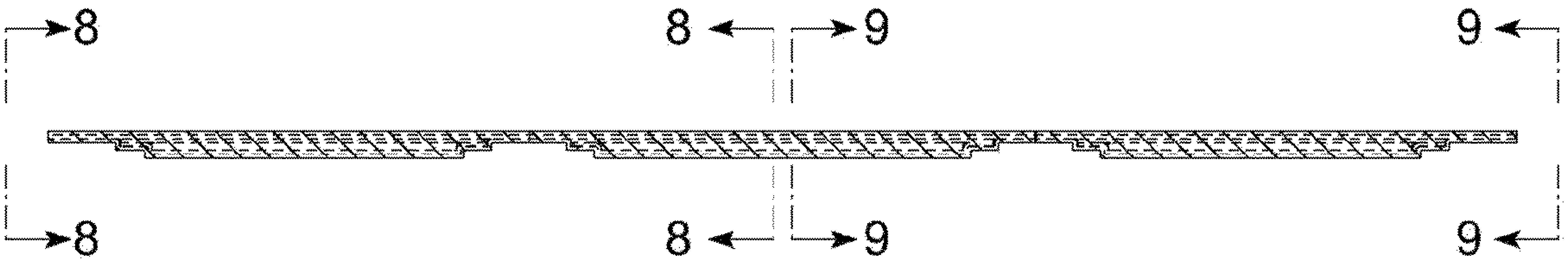

FIG. 7

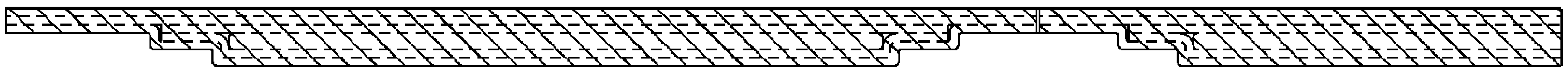

FIG. 8

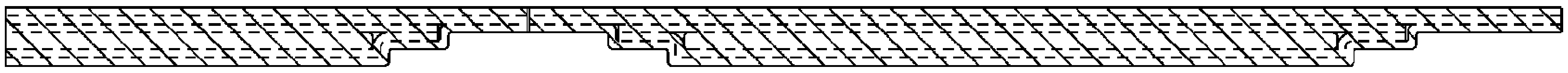

FIG. 9